

# 2SA1767

## Silicon PNP epitaxial planar type

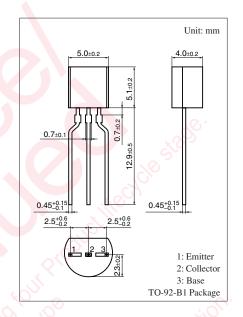
For general amplification Complementary to 2SC1473A

#### ■ Features

 $\bullet$  High collector-emitter voltage (Base open)  $V_{CEO}$ 

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	$V_{CBO}$	-300	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	-300	V	
Emitter-base voltage (Collector open)	$V_{EBO}$	-5	V	
Collector current	$I_{C}$	-70	mA	
Peak collector current	$I_{CP}$	-100	mA	
Collector power dissipation	$P_{C}$	750	mW	
Junction temperature	T <sub>j</sub>	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	



### ■ Electrical Characteristics T<sub>a</sub> = 25°C ± 3°C

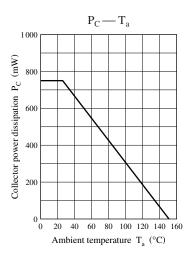
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = -100 \mu\text{A},  I_B = 0$	-300	9		V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = -1  \mu A,  I_C = 0$	-5			V
Forward current transfer ratio *	h <sub>FE</sub>	$V_{CE} = -10 \text{ V}, I_{C} = -5 \text{ mA}$	30		150	_
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = -10 \text{ mA}, I_B = -1 \text{ mA}$			- 0.6	V
Transition frequency	$f_T$	$V_{CB} = -10 \text{ V}, I_E = 10 \text{ mA}, f = 200 \text{ MHz}$		50		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		7		pF
(Common base, input open circuited)		The Ties				

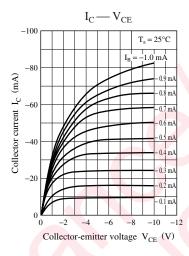
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

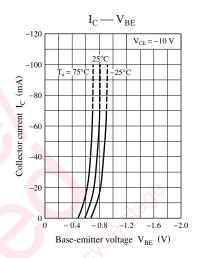
#### 2. \*: Rank classification

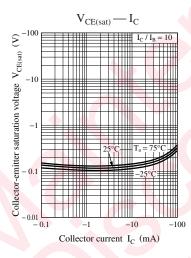
Rank	Р	Q			
$h_{ m FE}$	30 to 100	60 to 150			

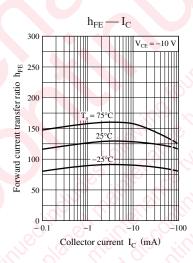
## **Panasonic**

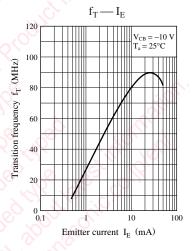


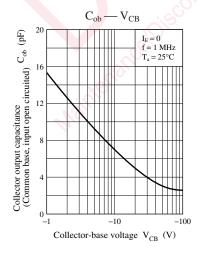


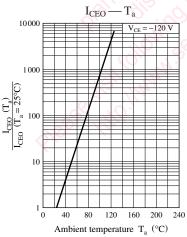












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